CLAIMS

~~1. A polishing composition for polishing a resin, the polishing composition comprising:~~

~~alumina abrasive grains;~~

~~a dispersant; and~~

~~water, wherein~~

~~a ratio between a primary average particle size of alumina particles in the alumina abrasive grains and an average particle size of the alumina particles measured by dynamic light scattering is 1:6.0 to 1:100.~~

~~2. The polishing composition according to claim 1, wherein~~

~~the dispersant is a surfactant.~~

~~3. The polishing composition according to claim 2, wherein~~

~~the surfactant is an alkylbenzenesulfonate.~~

1. An invention not claimed in any divisional application.